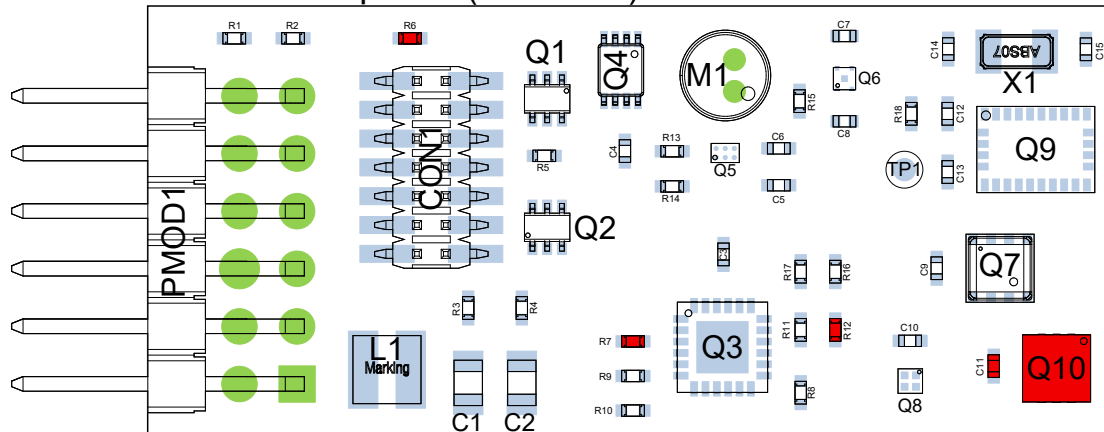


Bill Of Materials - Top side components 1/2

Designator	Comment	Quantity
C1, C2	47 μ F	2
C3, C4, C5, C9, C10, C12, C13	100 nF	7
C6	100 pF	1
C7, C8	2 μ 2	2
C14, C15	6p8	2
CON1	621 014 210 21	1
L1	10 μ H	1
M1	DB Unlimited electret condenser microphone	1
PMOD1	613 012 210 21	1
Q1, Q2	NUP4202W1T2G	2
Q3	PCA9655EMTTXG	1
Q4	NLAS323USG	1
Q5	FAN3852UC16X	1
Q6	NCP163AMX280TBG	1
Q7	BME680	1
Q8	LV0104CS-TLM-H	1
Q9	BNO055	1
R1, R2, R8, R9, R13, R14	0R	6
R3, R4	1R	2
R5, R10, R11	4k7	3
R15	3k3	1
R16, R17	2k7	2
R18	10k	1
X1	32.768 kHz 10ppm	1

View from Top side (Scale 3:1)



- ① Only components present in this assembly variant are listed in BoM table on the left
- ② Components not present in this assembly variant are crossed out by red line

MULTI-SENSE-GEVB

Revision:
2.2

State:
released

Variant name: standard_board

Engineer: T. Duris

Date: 5.Sep 2019 17:44PM

Assembly
document

Sheet
1 / 3

PCB File: MULTI-SENSE-GEVB.PcbDoc

Repository revision: locally modified 1251

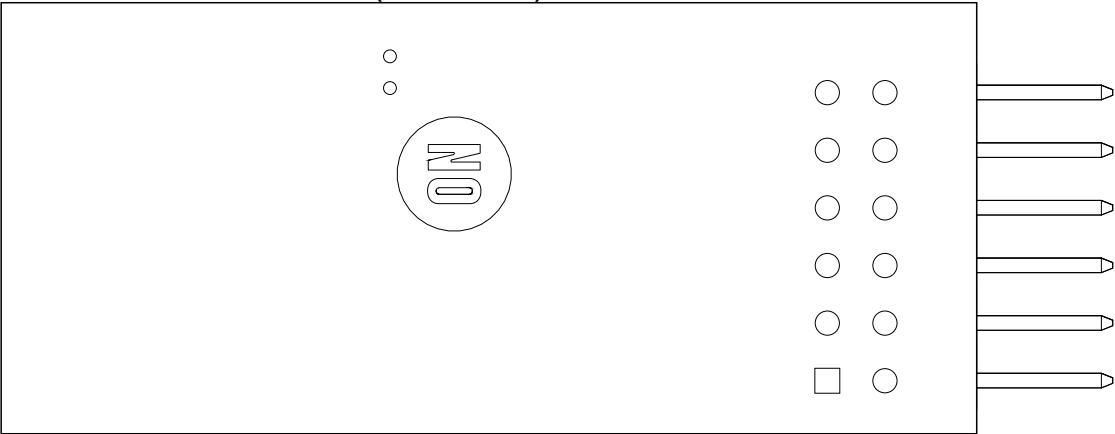
ON Semiconductor
Solution Engineering Center
Piestany



Bill Of Materials - Bottom side components 2/2

Designator	Comment	Quantity
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View from Bottom side (Scale 3:1)



- ③ Only components present in this assembly variant are listed in BoM table on the left
- ④ Components not present in this assembly variant are crossed out by red line

MULTI-SENSE-GEVB		Revision: 2.2	State: released
Variant name: standard_board		Assembly document	Sheet 2 / 3
Engineer: T. Duris	Date: 5.Sep 2019 17:44PM		
PCB File: MULTI-SENSE-GEVB.PcbDoc		ON Semiconductor Solution Engineering Center Piestany	
Repository revision: locally modified 1251			



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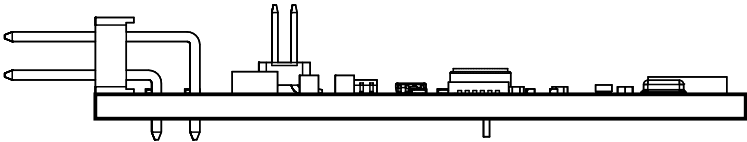
4

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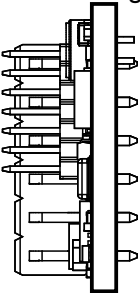
A

A

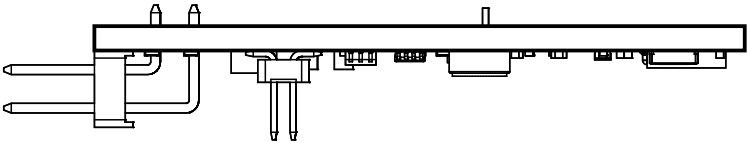
View from Front side (Scale 2:1)



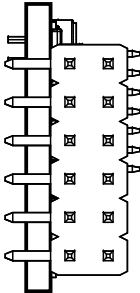
View from Right side (Scale 2:1)



View from Back side (Scale 2:1)



View from Left side (Scale 2:1)



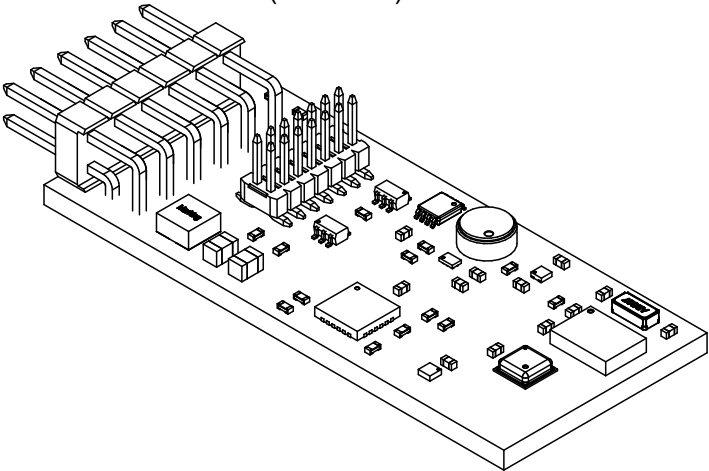
B

B

C

C

View from Front side (Scale 2:1)



D

D

MULTI-SENSE-GEVB		Revision: 2.2	State: released
Variant name: standard_board		Assembly document	Sheet 3 / 3
Engineer: T. Duris	Date: 5.Sep 2019 17:44PM		
PCB File: MULTI-SENSE-GEVB.PcbDoc		ON Semiconductor Solution Engineering Center Piestany	
Repository revision: locally modified 1251			

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